

Title (en)  
HEAT-RESISTANT POLYIMIDE BLENDS AND LAMINATES

Title (de)  
HITZEBESTÄNDIGE POLYIMIDMISCHUNGEN UND LAMINATE

Title (fr)  
MELANGES ET STRATIFIES DE POLYIMIDE THERMORESISTANTS

Publication  
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Application  
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Abstract (en)  
[origin: WO9502627A1] This invention relates to heat-resistant polyimide blends and molded parts thereof, which have excellent heat and moisture resistance, are relatively soluble in organic solvents, have excellent mechanical processability, and are suited for laminating and molding. The blends contain a thermoplastic polyimide component and a thermosetting imide oligomer. The weight ratio of the thermoplastic component to thermosetting component is selected in the range of 99/1 to 5/95. The thermoplastic polyimide component has a number average molecular weight of 10,000 or more.

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• See references of WO 9502627A1

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